

I claim:

1. A method of producing a wafer product, which comprises:

outputting a first wafer sheet with a sugar content of at least 23% or an equivalent content of a substance having the same technological properties as sugar from a baking oven;

applying to the first wafer sheet, while the first wafer sheet is in a hot state, a layer of a food product;

providing a second wafer sheet with a sugar content of at least 23% or an equivalent content of a substance having the same technological properties as sugar, and placing the second wafer sheet, while the second wafer sheet is in a hot state, on the first wafer sheet; and

subsequently compressing and spatially shaping the first and second hot wafer sheets containing the layer of the food product.

2. The method according to claim 1, which comprises placing onto the first wafer sheet a food product selected from the group consisting of a confection, meat product, fish product, cheese product, fruit product, vegetable product, nuts, and almonds.

3. The method according to claim 1, wherein the substance having the same technological properties as sugar is trehalose.

4. The method according to claim 1, which comprises cutting the pressed-together wafer sheets into individual hollow bodies and subsequently introducing a filling into the hollow bodies.

5. The method according to claim 1, which comprises cutting the spatially shaped wafer product into individual wafer products and providing the individual wafer products with an outer coating.

6. The method according to claim 1, which comprises processing, together with the first and second wafer sheets, additional hot wafer sheets with interposed layers of food products.

7. An assembly for producing wafer products according to claim 1, comprising:

an baking oven outputting hot wafer sheets;

a conveyor device adjacent said baking oven;

a lifting device for lifting a respective first wafer sheet of a pair of hot wafer sheets from said conveyor device;

a dosing device for depositing a food product onto a respective second wafer sheet of the pair of hot wafer sheets;
and

a processing device disposed to receive the pair of hot wafer sheets for pressing and shaping the two superimposed hot wafer sheets containing the layer of food product.

8. The assembly according to claim 7, wherein said baking oven is an automatically controlled baking oven.

9. The assembly according to claim 7, wherein said processing device is a shaping device.

10. The assembly according to claim 7, wherein said processing device is a suction device.

11. The assembly according to claim 7, which further comprises a separation device configured to divide the combined wafer sheets into individual hollow elements.

12. The assembly according to claim 11, wherein said separation device is a stamping device.

13. A wafer product, comprising a plurality of wafer sheets and intermediate layers of a food product disposed between respective said wafer sheets, combined by pressing and spatially shaped into individual wafer product.